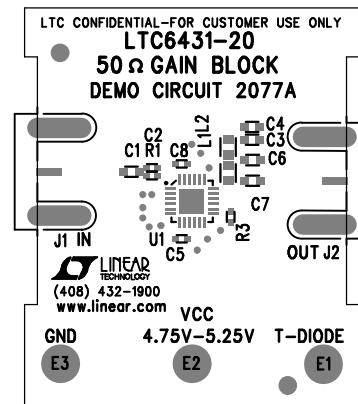


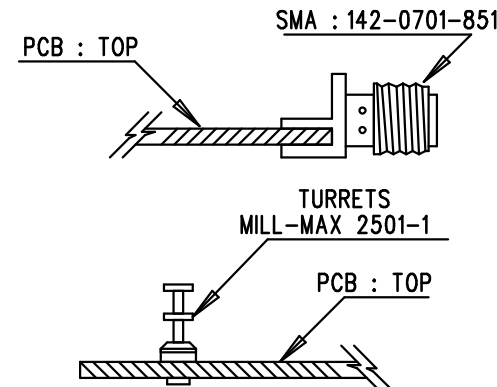
REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	1	1ST PROTOTYPE	JOHN C.	02-15-13


## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. NO SHUNT.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL SMA CONNECTORS AND TURRETS AS SHOWN BELOW:



TOP SILKSCREEN  
 LINEAR TECHNOLOGY  
 DC2077A-1  
 LTC6431-20  
 50  $\Omega$  GAIN BLOCK  
 DATE: 02-1513



APPROVALS		 <b>LINEAR TECHNOLOGY</b> 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY		
PCB DES.	AK			
APP ENG.	JOHN C.			
		TITLE: TOP ASSEMBLY DRAWING		
		50 $\Omega$ GAIN BLOCK		
		SIZE N/A	IC NO. LTC6431-20 DEMO CIRCUIT 2077A	REV. 1
SCALE = NONE		FILENAME: DC2077A-1.PCB		SHT 1 OF 1